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(12) **United States Design Patent**
Banerjee et al.

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(54) **ELECTRONIC DEVICE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (11) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/341**

(58) **Field of Classification Search**
USPC D14/341, 138 G, 138 AD, 138 R, 138 C,
D14/496, 203.1, 203.5, 203.7, 248;
D21/329, 517
CPC . G06F 1/1626; H04M 1/0266; H04M 1/0202;
H04M 1/026; H04M 1/0279
See application file for complete search history.

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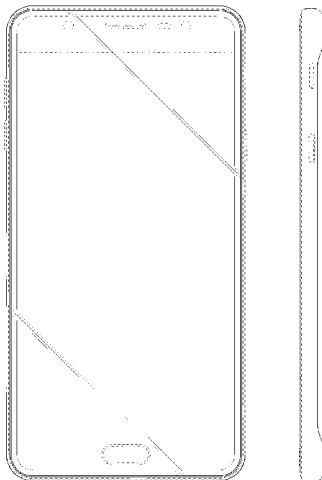
(57) **CLAIM**

We claim the ornamental design for an electronic device, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of an electronic device showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left-side elevational view thereof;
FIG. 5 is a right-side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof; and,
FIG. 8 is a rear perspective view thereof.
The broken lines shown in the drawings depict portions of the electronic device that form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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FIG.1

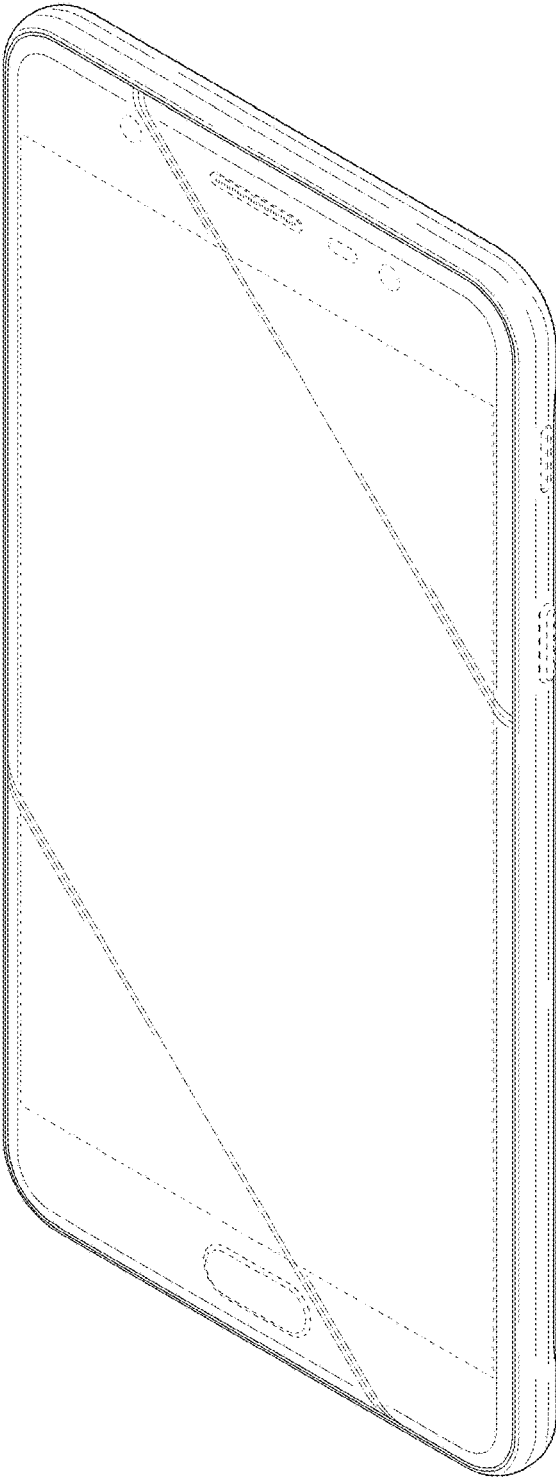


FIG.2

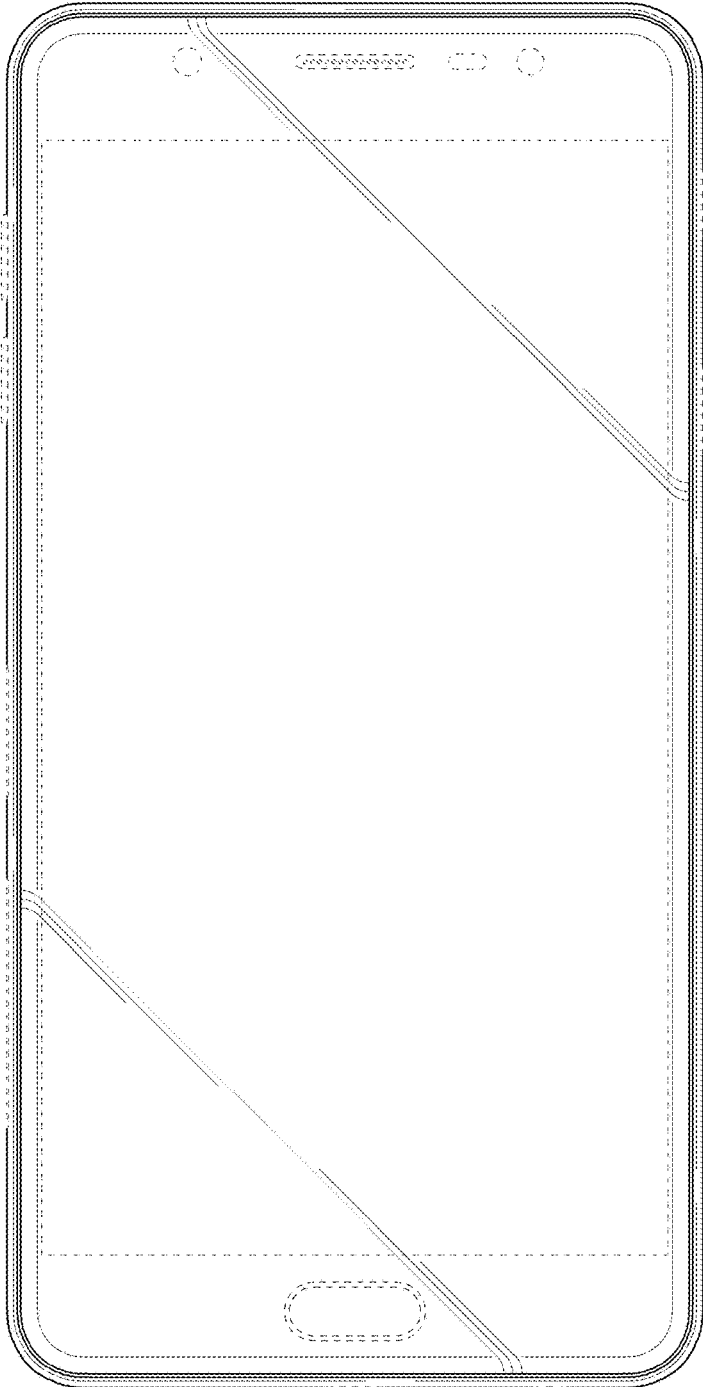


FIG.3

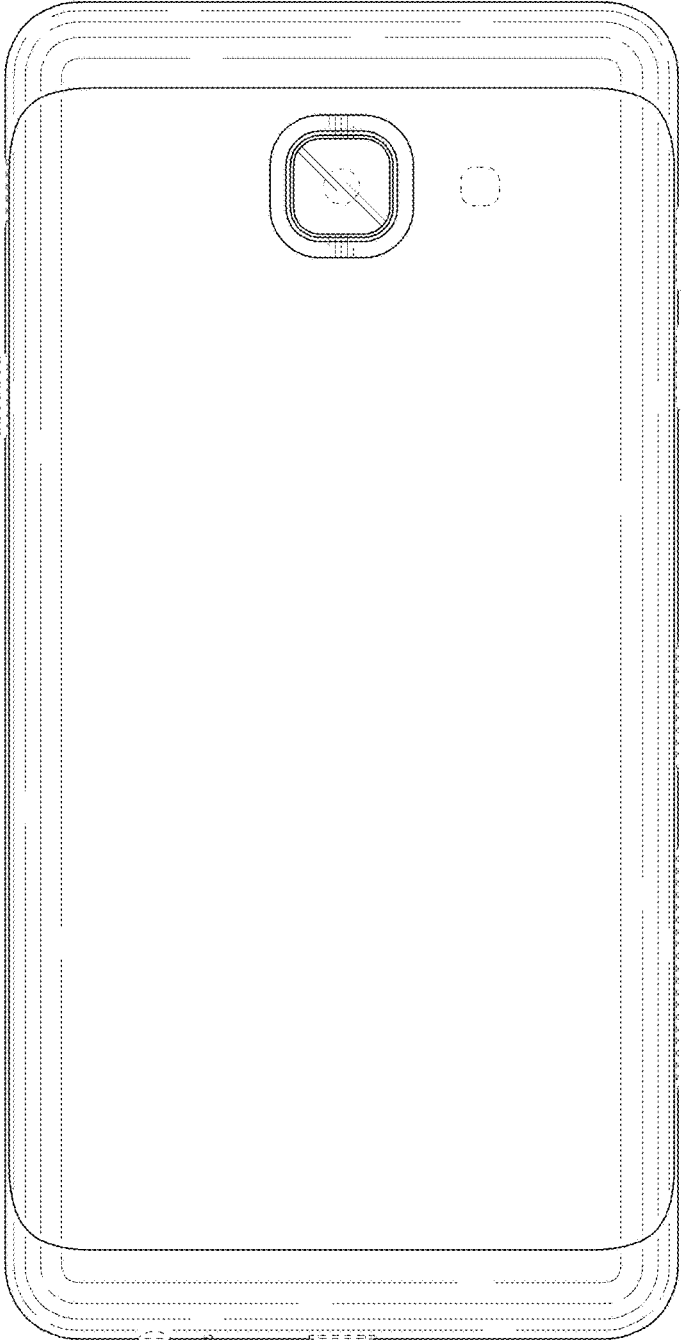


FIG.4

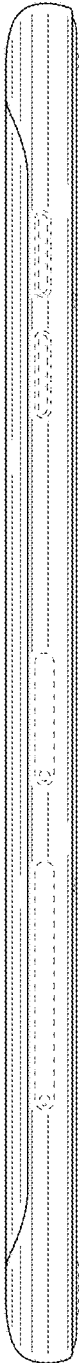


FIG.5

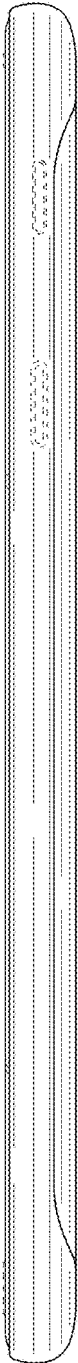


FIG.6

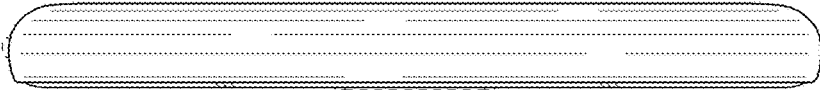


FIG.7

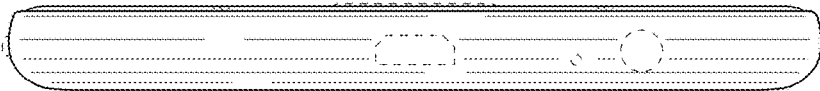


FIG.8

